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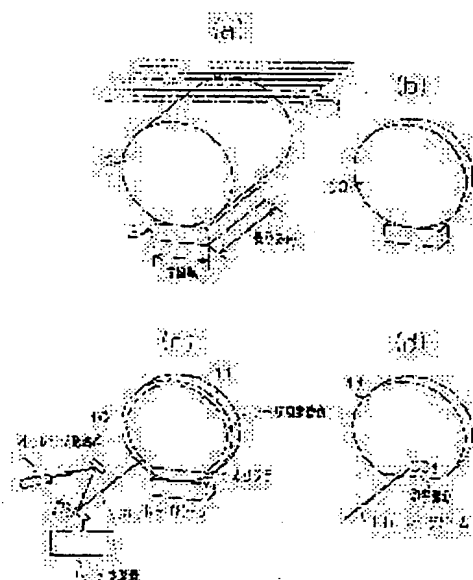
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## (54) SEMICONDUCTOR SUBSTRATE MANUFACTURING METHOD AND APPARATUS THEREOF

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To easily manufacture a semiconductor substrate into a novel structure with a desired shape and size.

**SOLUTION:** A cylindrical ingot 1 is sliced in a prescribed thickness and formed into disc-like wafers 10. A laser beam Lb is irradiated on the disc-like wafer 10 to cut the wafer 10 into a wafer 11 of a desired shape and size.



## LEGAL STATUS

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